

Amendments to the Claims

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-11 (Canceled)

Claim 12 (Currently Amended): A semiconductor device, comprising:

a semiconductor element having a first surface and a second surface, the first surface being an opposite surface with respect to the second surface of the semiconductor element;

an electrode at the first surface of the semiconductor element;

a wiring portion on the first surface of the semiconductor element and connected to the electrode;

a conductive post on the first surface of the semiconductor element and connected to the wiring portion;

a resin layer on the first surface of the semiconductor element, the resin layer covers the first surface of the semiconductor element, the wiring portion and a side of the conductive post;

an external connection on the conductive post; and

a protective layer made of polyimide resin on the second surface of the

semiconductor element,

wherein an end portion of the protective layer is aligned with both an end portion of the semiconductor element and an end portion of the resin layer, and wherein the end portions of the protective layer, the semiconductor element and the resin layer define an outer edge of the semiconductor device, and

wherein the protective layer is a peelably removable UV sensitive tape comprised of a hardened synthetic resin that bonds the tape to the second surface of the semiconductor element.

Claims 13-14 (Canceled)

Claim 15 (Previously Presented): A semiconductor device according to claim 12, wherein the external connection is a solder ball.

Claim 16 (Previously Presented): A semiconductor device according to claim 12, wherein the conductive post is comprised of copper.

Claim 17 (Currently Amended): A semiconductor device, comprising:

a semiconductor element having a first surface and a second surface, the first surface being an opposite surface with respect to the second surface of the semiconductor element;

an electrode at the first surface of the semiconductor element;

a wiring portion on the first surface of the semiconductor element and connected to the electrode;

a conductive post on the first surface of the semiconductor element and connected to the wiring portion;

a resin layer on the first surface of the semiconductor element, the resin layer covers the first surface of the semiconductor element, the wiring portion and a side of the conductive post;

an external connection on the conductive post; and

a protective layer made of polyimide resin on the second surface of the semiconductor element,

wherein a side surface of the semiconductor element is exposed from the resin layer and the protective layer, wherein an end portion of the protective layer is aligned with both the exposed side surface of the semiconductor element and an end portion of the resin layer, and wherein the end portions of the protective layer and the resin layer, and the exposed side surface of the semiconductor element define an outer edge of the semiconductor device, and

wherein the protective layer is a peelably removable UV sensitive tape which comprises a hardened synthetic resin that bonds the tape to the second surface of the semiconductor element.

Claims 18-19 (Canceled)

Claim 20 (Previously Presented): A semiconductor device according to claim 17,
wherein the external connection is a solder ball.

Claim 21 (Previously Presented): A semiconductor device according to claim 17,
wherein the conductive post is comprised of copper.

Claim 22 (Currently Amended): A semiconductor device, comprising:

- a semiconductor element having a first surface and a second surface, the first surface being an opposite surface with respect to the second surface of the semiconductor element;

- an electrode at the first surface of the semiconductor element;

- a wiring portion on the first surface of the semiconductor element and connected to the electrode;

- a conductive post on the first surface of the semiconductor element, the conductive post having a first end portion connected to the wiring portion and a second end portion;

- a resin layer on the first surface of the semiconductor element, the resin layer covers the first surface of the semiconductor element, the wiring portion and a side of the conductive post, and wherein the second end portion of the conductive post is not

covered by the resin layer;

an external connection on the second end portion of the conductive post; and

a protective layer made of polyimide resin on the second surface of the semiconductor element,

wherein only a side surface of the semiconductor element is exposed from the resin layer and the protective layer, wherein an end portion of the protective layer is aligned with both the side surface of the semiconductor element and an end portion of the resin layer, and wherein the end portions of the protective layer and the resin layer, and the side surface of the semiconductor element define an outer edge of the semiconductor device, and

wherein the protective layer is a peelably removable UV sensitive tape which comprises a hardened synthetic resin that bonds the tape to the second surface of the semiconductor element.

Claims 23-24 (Canceled)

Claim 25 (Previously Presented): A semiconductor device according to claim 22, wherein the external connection is a solder ball.

Claim 26 (Previously Presented): A semiconductor device according to claim 22, wherein the conductive post is comprised of copper.

Claim 27 (Currently Amended): A semiconductor device, comprising:

a semiconductor element having a first surface and a second surface, the first surface being an opposite surface with respect to the second surface of the semiconductor element;

an electrode at the first surface of the semiconductor element;

a wiring portion on the first surface of the semiconductor element and connected to the electrode;

a conductive post on the first surface of the semiconductor element and connected to the wiring portion;

a resin layer on the first surface of the semiconductor element, the resin layer covers the first surface of the semiconductor element, the wiring portion and a side of the conductive post;

an external connection terminal on the conductive post; and

a protective layer made of polyimide resin on the second surface of the semiconductor element,

wherein a side surface of the protective layer is in a same plane with both a side surface of the semiconductor element and a side surface of the resin layer, and wherein the side surfaces of the protective layer, the semiconductor element and the resin layer define an outer edge of the semiconductor device, and

wherein the protective layer is a peelably removable UV sensitive tape comprised of a hardened synthetic resin that bonds the tape to the second surface of

the semiconductor element.

Claims 28-29 (Canceled)

Claim 30 (Previously Presented): A semiconductor device according to claim 27,
wherein the external connection terminal is a solder ball.

Claim 31 (Previously Presented): A semiconductor device according to claim 27,
wherein the conductive post is comprised of copper.